









Release Date: 26 June 2022 Version: A1.1

PRODUCT DATASHEET



- ► SuperFlux
- ▶ 3mm Round 4.4t
- ➤ Yellow (590nm)

NOY50P35S-70MA



SuperFux Series





SuperFlux Series

APPLICATIONS:

- **Decorative Lighting**
- Indicator
- Commercial Lighting

FEATURES:

- Package: THT Through Hole 4 Pins Package
- Forward Current: 70mA Forward Voltage (typ.): 2.9V
- Luminous Flux (typ.): 7.0lm@70mA
- Colour: Yellow
- Wavelength: 590nm Viewing angle: 70°
- **Materials:**
 - Die: AlGaInP
 - Resin: Epoxy (Water Clear)
 - L/T Finish: Ag plated
- Operating Temperature: -40~+85°C Storage Temperature: -40~+100°C
- **Grouping parameters:**
 - Forward voltage
 - Luminous flux
 - Dominant wavelength
- Soldering methods: DIP Iron or Wave Soldering
- Preconditioning: acc. to JEDEC Level 3
- Packing: 60pcs/tube; 6300pcs/carton



CHARACTERISTICS:

Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
Forward Current	I _F	70	mA
Peak Forward Current (Duty 1/10; width 10KHz)	I _{FP}	90	mA
Reverse Voltage	V _R	5	V
Reverse Current @5V	I _R	10	μΑ
Power Dissipation	P _D	120	mW
Electrostatic Discharge	ESD	2000	V
Operating Temperature	T _{OPR}	-40~+85	°C
Storage Temperature	T _{STG}	-40~+100	°C

Electrical & Optical Characteristics (Ta=25°C)

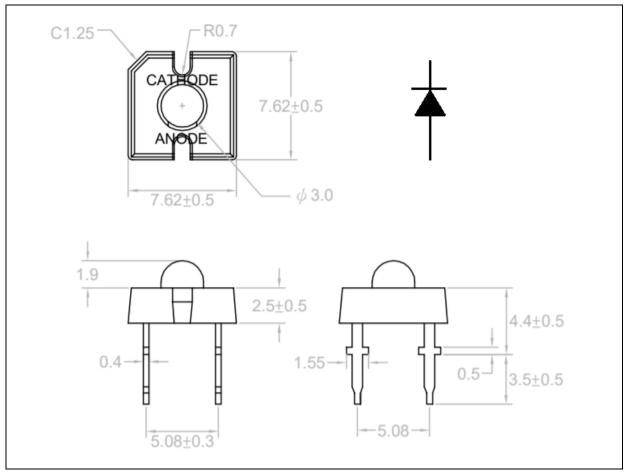
Parameter	Symbol	Values			Unit	Test
Parameter		Min.	Тур.	Max.	Unit	Condition
Forward Voltage	VF	2.3		3.5	V	I _F =70mA
Luminous Flux	Ф۷	6.0	7.0		lm	I _F =70mA
Dominant Wavelength	λ_{D}		590		nm	I _F =70mA
Spectral Half Width	Δλ		20		nm	I _F =70mA
Viewing Angle	2θ _{1/2}		70		deg	I _F =70mA

^{1.} Luminous intensity (I $_{V}$) $\pm 10\%$, Forward Voltage (V $_{F}$) $\pm 0.1V$



OUTLINE DIMENSION:

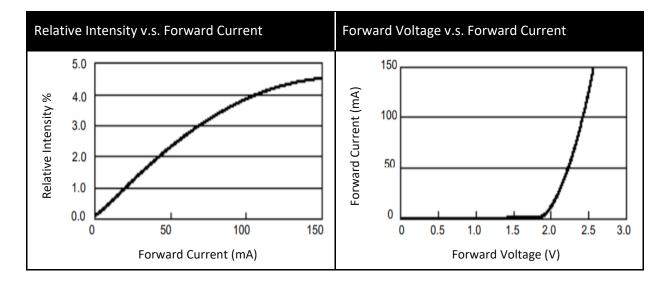
Package Dimension:

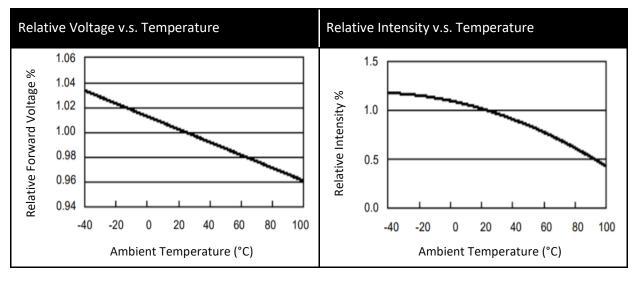


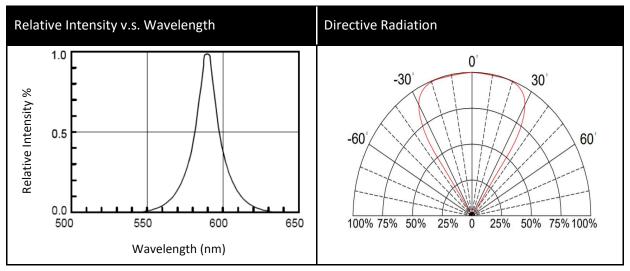
- 1. All dimensions are in millimetre (mm).
- 2. Tolerance ±0.2mm, unless otherwise noted.



ELECTRO-OPTICAL CHARACTERISTICS:







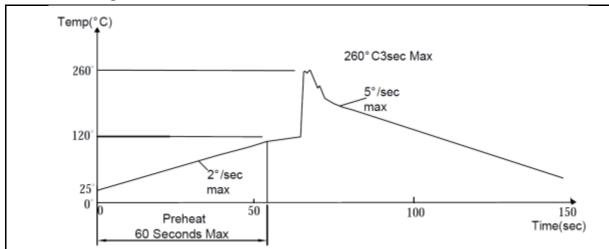


RECOMMENDED SOLDERING PROFILE:

DIP Iron:

- Soldering Iron 30W Max.
- Temperature 350°C Max.
- Soldering Time 3 seconds Max. One time only.
- Distance 2mm Min. (from solder joint to body).

Wave Soldering Profile:



Dip Soldering

• Preheat: 120°C Max

Preheat time: 60seconds Max

Ramp-up

2°C/sec(max)

Ramp-Down: -5°C/sec(max)

Solder Bath: 260°C Max

• Dipping Time: 3 seconds Max

• Distance: 2mm Min (From solder joint to body)

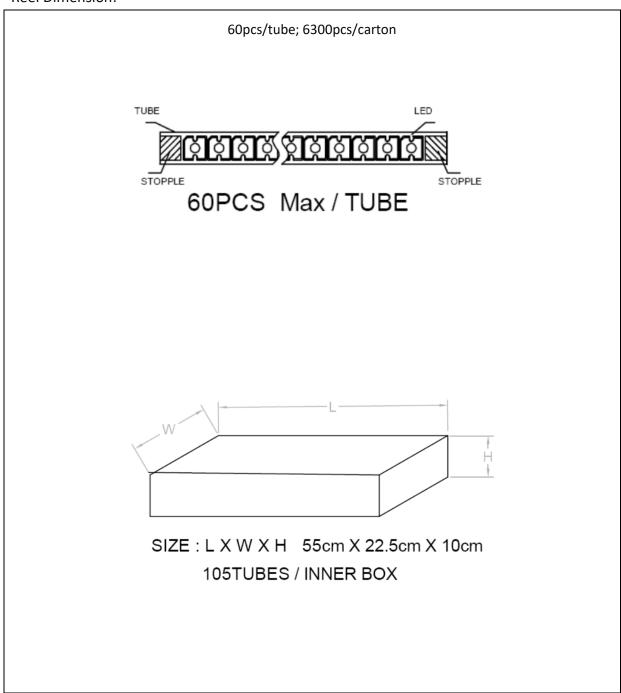
Note:

- 1. Maximum reflow soldering: 1 time.
- 2. Before, during, and after soldering, should not apply stress on the components and PCB board.
- 3. Recommended reflow temperature 240°C. The maximum soldering temperature should be limited to 260°C.



PACKING SPECIFICATION:

Reel Dimension:





PRECAUTIONS OF USE:

Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 months at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with descanting agent <10% R.H. and apply baking.

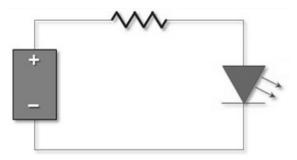
Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

• 60±3°C x 24hrs and <5%RH, taped / reel package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

Testing Circuit:



Must apply resistor(s) for protection (over current proof).

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.



REVISION RECORD:

Version	Date	Summary of Revision
A1.0	05/10/2006	Datasheet set-up.
A1.1	26/06/2022	New datasheet format.